



Click [here](#) for the 3D model.

Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	SMD COTS COG
Style	SMD Chip
Description	SMD, MLCC, COTS, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
Failure Rate	Testing per MIL-PRF-55681 PDA 8%, DPA per EIA-469, Humidity per MIL-STD-202, Method 103, Condition A
AEC-Q200	No
Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	22 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms